

Customer Information Notification

Issue Date:02-Jan-2014Effective Date:03-Feb-2014

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to <u>view this notification online</u>



QUALITY

Management Summary

NXP will introduce new reel design for lighter packing using less material.

Change Category

- [] Wafer Fab process
- [] Wafer Fab materials [] Wafer Fab location
- [] Assembly Process [] Assembly Materials [] Assembly Location

[] Product Marking

[] Test Location

[] Electrical spec./Test coverage

[] Design

[] Mechanical Specification [X] Packing/Shipping/Labeling

Introducing lighter reels for tape & reel packing at APG and APM

Information Notification

As announced through GN 2013100002 NXP will introduce a new reel design using less materials.

Through this CIN NXP communicates the introduction of three reels at assembly sites APG and APM. These reels have been tested and fulfil our packing requirements and are in compliance with EIA-481D and IEC60286-3.

Conversion for the products in this phase will start per February 2014, to be finalized in 2014 (please see remark).

Stock of reels with 'old' design will be used up before delivery of products in light weight reels will start. In the conversion period current and light weight reels might be mixed, but considering the fact that they are fully compatible, this will not hamper processing at customers.

For detailed information we invite you to view this notification online where a file is attached which indicates what the

change looks like and what has been tested to release this.

Why do we issue this Information Notification

This change enables environmental improvement by reducing waste materials.

Identification of Affected Products

Products from APG and APM can be identified by the country of origin information on the packing label or by the vendor code on the product marking (if space permits).

Impact

No impact to the product's functionality anticipated. The major dimensions will not change, reels are fully compatible with the reels currently used.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Remarks

As soon as we have a more detailed (monthly / weekly) planning we will put this in the CIN, see details as indicated on page 1.

Attached to this CIN:

A one page powerpoint presentation showing reel examples and a table showing tests that will be done to release the reels.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please <u>contact NXP "Global Quality Support</u> <u>Team"</u>.

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

 Name
 GA Customer Support

 e-mail address
 DiscrQA.Helpdesk.GA-Products@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

A global semiconductor company with operations in more than 25 countries, NXP posted unaudited revenue of \$4.36 billion in 2012.

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